Product Change Notification: CBOL-24RMAK490

Date:

02-Jul-2026

Product Category:

Linear Op Amps, Switching Regulators

Notification Subject:

CCB 8371 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for MCP6061T-E/MNY, MCP6051T-E/MNY, MCP6071T-E/MNY, MCP6052T-E/MNY, MCP6062T-E/MNY, MCP6072T-E/MNY, MCP6232T-E/MNY, MCP6402T-E/MNY, MCP6442T-E/MNY, MCP6V01T-E/MNY, MCP6V03T-E/MNY, MCP6V06T-E/MNY, MCP6V08T-E/MNY, MCP6V26T-E/MNY, MCP6V28T-E/MNY, MCP621T-E/MNY, MCP651T-E/MNY, MCP631T-E/MNY, MCP661T-E/MNY, MCP16252T-I/MNY and MCP16251T-I/MNY catalog part numbers (CPN) available in 8L TDFN (2x3x0.8mm) package at MMT assembly site.

Affected CPNs:

CBOL-24RMAK490_Affected_CPN_07022026.pdf
CBOL-24RMAK490_Affected_CPN_07022026.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for MCP6061T-E/MNY, MCP6051T-E/MNY, MCP6071T-E/MNY, MCP6052T-E/MNY, MCP6062T-E/MNY, MCP6072T-E/MNY, MCP6232T-E/MNY, MCP6402T-E/MNY, MCP6442T-E/MNY, MCP6V01T-E/MNY, MCP6V03T-E/MNY, MCP6V06T-E/MNY, MCP6V08T-E/MNY, MCP6V26T-E/MNY, MCP6V28T-E/MNY, MCP621T-E/MNY, MCP651T-E/MNY, MCP631T-E/MNY, MCP661T-E/MNY, MCP16252T-I/MNY and MCP16251T-I/MNY catalog part numbers (CPN) available in 8L TDFN (2x3x0.8mm) package at MMT assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)
Assembly Site	Microchip Technology Thailand (Branch) (MMT)	Microchip Technology Thailand (Branch) (MMT)	No
Wire Material	Au	CuPdAu	Yes
Die Attach Material	QMI519 (PFAS-free)	QMI519 (PFAS-free)	No
Molding Compound Material	G700LTD	G700LTD	No
Lead-Frame Material	A194	A194	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material.

Change Implementation Status: In Progress

Estimated First Ship Date: 23 September 2026 (date code: 2639)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	July 2026					>	**September 2026**				
Work Week	27	28	29	30	31		36	37	38	39	40
Qual Report Availability	X										
Final PCN Issue Date	X										
Estimated Implementation Date										X	

Method to Identify Change: Traceability Code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Note: This is a qualification by similarity (QBS) to CCB#7222 and CCB#4732.

Revision History: July 2, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_CBOL-24RMAK490_Qual Report_CCB4732.pdf
PCN_CBOL-24RMAK490_Qual Report_CCB7222.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

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If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

MCP16252T-I/MNY

MCP16251T-I/MNY

MCP6061T-E/MNY

MCP6051T-E/MNY

MCP6071T-E/MNY

MCP6052T-E/MNY

MCP6062T-E/MNY

MCP6072T-E/MNY

MCP6232T-E/MNY

MCP6402T-E/MNY

MCP6442T-E/MNY

MCP6V01T-E/MNY

MCP6V03T-E/MNY

MCP6V06T-E/MNY

MCP6V08T-E/MNY

MCP6V26T-E/MNY

MCP6V28T-E/MNY

MCP621T-E/MNY

MCP651T-E/MNY

MCP631T-E/MNY

MCP661T-E/MNY

Qualification Report Summary

RELIABILITY LABORATORY

PCN #: CBOL-24RMAK490

Date: October 6, 2021

Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for MCP6061T-E/MNY, MCP6051T-E/MNY, MCP6071T-E/MNY, MCP6052T-E/MNY, MCP6062T-E/MNY, MCP6072T-E/MNY, MCP6232T-E/MNY, MCP6402T-E/MNY, MCP6442T-E/MNY, MCP6V01T-E/MNY, MCP6V03T-E/MNY, MCP6V06T-E/MNY, MCP6V08T-E/MNY, MCP6V26T-E/MNY, MCP6V28T-E/MNY, MCP621T-E/MNY, MCP651T-E/MNY, MCP631T-E/MNY, MCP661T-E/MNY, MCP16252T-I/MNY and MCP16251T-I/MNY catalog part numbers (CPN) available in 8L TDFN (2x3x0.8mm) package at MMT assembly site. This is Q006 grade 1 qualification.

PACKAGE QUALIFICATION REPORT

Purpose:

Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for MCP6061T-E/MNY, MCP6051T-E/MNY, MCP6071T-E/MNY, MCP6052T-E/MNY, MCP6062T-E/MNY, MCP6072T-E/MNY, MCP6232T-E/MNY, MCP6402T-E/MNY, MCP6442T-E/MNY, MCP6V01T-E/MNY, MCP6V03T-E/MNY, MCP6V06T-E/MNY, MCP6V08T-E/MNY, MCP6V26T-E/MNY, MCP6V28T-E/MNY, MCP621T-E/MNY, MCP651T-E/MNY, MCP631T-E/MNY, MCP661T-E/MNY, MCP16252T-I/MNY and MCP16251T-I/MNY catalog part numbers (CPN) available in 8L TDFN (2x3x0.8mm) package at MMT assembly site. This is Q006 grade 1 qualification.

CN:	ES359035
QUAL ID:	R2100665 Rev. A
MP CODE:	A7CJ14B3XA00
Part No.:	MCP6031-E/MC
Bonding No.:	BDM-002966 Rev. A
CCB No.:	4732

Lead Frame

Paddle Size:	75 x 67 mils
Material:	C194
Surface:	Bare Cu
Process:	Etched
Lead Lock:	Yes
Part Number:	10100852
Plating Composition:	Matte Sn

Bond Wire

Wire:	CuPdAu wire

Die Attach Material

Epoxy:	3280

Mold Compound

Mold Compound:	G700LTD

Package

Type:	8L DFN
Package Size:	2 x 3 x 0.9 mm

PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MMT-221102373.000	TMPE221475584.100	2123R6P
MMT-221200863.000	TMPE221475584.100	2124TPP
MMT-221200864.000	TMPE221475584.100	2124TQG

Result: **Pass**

Conclusion:

8L DFN (2x3x0.9 mm) assembled by MMT pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Moisture/Reflow Sensitivity Classification Test (At MSL Level 1)	85°C/ 85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 (IPC/JEDEC J-STD-020E)	IPC/JEDEC J-STD-020E	135	0/135	Pass	

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Precondition Prior Perform Reliability Tests (At MSL Level 1)	Electrical Test: +25°C, 85°C and 125°C System: ETS300	JESD22-A113	693(0)	693		Good Devices
	Bake 150°C, 24 hrs System: CHINEE		693	693		
	85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH		693	693		
	3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243		693	693		
	Electrical Test: +25°C, 85°C and 125°C System: ETS300		693(0)	0/693	Pass	

PACKAGE QUALIFICATION REPORT

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Temp Cycle	Stress Condition: -65°C to +150°C, 500 Cycles System: TABAI ESPEC TSA-70H Electrical Test: + 85°C and 125°C System: ETS300	JESD22-A104	231(0)	0/231	Pass	Parts had been pre-conditioned at 260°C
	Wire Pull (>2.5 grams)		45(0)	0/45	Pass	
	Bond Shear (>15.00 grams)		3(0)	0/3	Pass	1 Wire/ lot
	Stress Condition: -65°C to +150°C, 1000 Cycles System: TABAI ESPEC TSA-70H Electrical Test: + 85°C and 125°C System: ETS300		231(0)	0/231	Pass	
	Wire Pull (>2.5 grams)		45(0)	0/45	Pass	
	Bond Shear (>15.00 grams)		3(0)	0/3	Pass	1 Wire/ lot

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
HAST	Stress Condition: +130°C/85%RH, 96 hrs. Bias Volt: 5.5 Volts System: HAST 6000X Electrical Test: +25°C, 85°C and 125°C System: ETS300	JESD22-A110	231(0)	0/231	Pass	Parts had been pre-conditioned at 260°C 77 units / lot
	Wire Pull (>2.5 grams)		45(0)	0/45	Pass	
	Bond Shear (>15.00 grams)		3(0)	0/3	Pass	1Wire/ lot
	Stress Condition: +130°C/85%RH, 192 hrs. Bias Volt: 5.5 Volts System: HAST 6000X Electrical Test: +25°C, 85°C and 125°C System: ETS300		231(0)	0/231	Pass	
	Wire Pull (>2.5 grams)		45(0)	0/45	Pass	
	Bond Shear (>15.00 grams)		3(0)	0/3	Pass	1 Wire/ lot

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
UNBIASED-HAST	Stress Condition: +130°C/85%RH, 96 hrs. System: HAST 6000X Electrical Test: +25°C System: ETS300	JESD22-A118	231(0)	0/231	Pass	Parts had been pre-conditioned at 260°C 77 units / lot

PACKAGE QUALIFICATION REPORT

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
High Temperature Storage Life	Stress Condition: Bake 175°C, 500 hrs System: SHEL LAB Electrical Test: +25°C, 85°C and 125°C System: ETS300	JESD22-A103	135(0)	0/135	Pass	45 units / lot
	Bond Shear (>15.00 grams) / Cross section		3(0)	0/3	Pass	1 Wire/ lot
	Stress Condition: Bake 175°C, 1000 hrs System: SHEL LAB Electrical Test: +25°C, 85°C and 125°C System: ETS300		135(0)	0/135	Pass	
	Bond Shear (>15.00 grams) / Cross section		3(0)	0/3	Pass	1 Wire/ lot

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Solderability Temp 245°C	Steam Aging: Temp 93°C, 8Hrs System: SAS-3000 Solder Dipping: Solder Temp. 245°C Solder material: Pb Free Sn 95.5Ag3.9 Cu0.6 System: ERSA RA 2200D Visual Inspection: External Visual Inspection	J-STD-002	22(0)	0/22	Pass	

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Physical Dimensions	Physical Dimension, 10 units from 1 lot	JESD22-B100/B 108	30(0)	0/30	Pass	

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Bond Strength Data Assembly	Wire Pull (> 2.5 grams)	Mil. Std. 883-2011	30(0)	0/30	Pass	
	Bond Shear (>15.00 grams)	CDF-AEC-Q100 -001	30(0)	0/30	Pass	

Qualification Report Summary

RELIABILITY LABORATORY

PCN #: CBOL-24RMAK490

Date: June 26, 2026

Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for MCP6061T-E/MNY, MCP6051T-E/MNY, MCP6071T-E/MNY, MCP6052T-E/MNY, MCP6062T-E/MNY, MCP6072T-E/MNY, MCP6232T-E/MNY, MCP6402T-E/MNY, MCP6442T-E/MNY, MCP6V01T-E/MNY, MCP6V03T-E/MNY, MCP6V06T-E/MNY, MCP6V08T-E/MNY, MCP6V26T-E/MNY, MCP6V28T-E/MNY, MCP621T-E/MNY, MCP651T-E/MNY, MCP631T-E/MNY, MCP661T-E/MNY, MCP16252T-I/MNY and MCP16251T-I/MNY catalog part numbers (CPN) available in 8L TDFN (2x3x0.8mm) package at MMT assembly site. This is a Q100 grade 1 qualification.

PACKAGE QUALIFICATION REPORT

Purpose:

Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for MCP6061T-E/MNY, MCP6051T-E/MNY, MCP6071T-E/MNY, MCP6052T-E/MNY, MCP6062T-E/MNY, MCP6072T-E/MNY, MCP6232T-E/MNY, MCP6402T-E/MNY, MCP6442T-E/MNY, MCP6V01T-E/MNY, MCP6V03T-E/MNY, MCP6V06T-E/MNY, MCP6V08T-E/MNY, MCP6V26T-E/MNY, MCP6V28T-E/MNY, MCP621T-E/MNY, MCP651T-E/MNY, MCP631T-E/MNY, MCP661T-E/MNY, MCP16252T-I/MNY and MCP16251T-I/MNY catalog part numbers (CPN) available in 8L TDFN (2x3x0.8mm) package at MMT assembly site. This is a Q100 grade 1 qualification.

CN:	E000249619
QUAL ID:	R2401383 Rev. B
MP CODE:	GBCB2Y5QXA00
Part No.:	MCP651T-E/MNY
Bonding No.:	BD-002690 Rev. 01
CCB No.:	7222

Lead Frame

Paddle Size:	83 x 71mils
Material:	A194
Surface:	NiPdAu
Process:	Etched
Lead Lock:	No
Part Number:	10100853
Plating Composition:	NiPdAu

Bond Wire

Wire:	Au wire

Die Attach Material

Epoxy:	QMI519

Mold Compound

Mold Compound:	G700LTD

Package

Type:	8L TDFN
Package Size:	2 x 3 x 0.8mm

PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MMT-253100458.000	TMPE224148892.130	2444UWY
MMT-253100893.000	TMPE224148892.130	2444WQM
MMT-253100894.000	TMPE224148892.130	2444WQP

Result: **Pass**

Conclusion:

8L TDFN (2 x 3 x 0.8mm) assembled by MMT pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Precondition Prior Perform Reliability Tests (At MSL Level 1)	Electrical Test: +25°C and 125°C System: ETS300 Bake 150°C, 24 hrs. System: CHINEE 85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 Electrical Test: +25°C and 125°C System: ETS300	JESD22-A113 JIP/IPC/JEDEC J-STD-020E	693(0)	0/693	Pass	Good Devices

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Temp Cycle	Stress Condition: -55°C to +150°C, 1000 Cycles System: TABAI ESPEC TSA-70H Electrical Test: +25°C and 125°C System: ETS300	JESD22-A104	231(0)	0/231	Pass	Parts had been pre-conditioned at 260°C 77 units / lot
	Bond Strength: Wire Pull (>2.50 grams)	JESD22-A104	15(0)	0/15	Pass	

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
UNBIASED-HAST	Stress Condition: +130°C/85%RH, 96 hrs. System: HAST 6000X Electrical Test: +25°C System: ETS300	JESD22-A118	231(0)	0/231	Pass	Parts had been pre-conditioned at 260°C 77 units / lot

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
HAST	Stress Condition: +130°C/85%RH, 96 hrs. Bias Volt: 6.0 Volts System: HAST 6000X Electrical Test: +25°C and 125°C System: ETS300	JESD22-A110	231(0)	0/231	Pass	Parts had been pre-conditioned at 260°C 77 units / lot

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
High Temperature Storage Life	Stress Condition: Bake 175°C, 500 hrs. System: TPS Bake Oven Electrical Test: +25°C and 125°C System: ETS300	JESD22-A103	45(0)	0/45	Pass	45 units

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Solderability Temp 215°C	Steam Aging: Temp 93°C, 1Hrs. System: SAS-3000 Solder Dipping: Solder Temp.215°C Solder material: SnPb Sn63, Pb37 System: ERSA RA 2200D Visual Inspection: External Visual Inspection	J-STD-002	22(0)	0/22	Pass	

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Solderability Temp 245°C	Steam Aging: Temp 93°C, 1Hrs. System: SAS-3000 Solder Dipping: Solder Temp.245°C Solder material: Pb Free Sn 95.5Ag3.9 Cu0.6 System: ERSA RA 2200D Visual Inspection: External Visual Inspection	J-STD-002	22(0)	0/22	Pass	

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Bond Strength Data Assembly	Wire Pull (>2.50 grams) Bond Shear (>15.00 grams)	Mil. Std. 883-2011 CDF-AEC-Q100-001	30(0) Wires 30(0) bonds	0/30 0/30	Pass	